

International IOR Rectifier

HEXFET® POWER MOSFET

Provisional Data Sheet No. PD-9.552B

JANTX2N6845

JANTXV2N6845

[REF:MIL-PRF-19500/563]

[GENERIC:IRFF9120]

P-CHANNEL

-100 Volt, 0.60Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance. HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

Product Summary

Part Number	BV _{DSS}	R _{DS(on)}	I _D
JANTX2N6845	-100V	0.60Ω	-4.0A
JANTXV2N6845			

Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

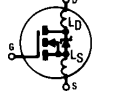
Absolute Maximum Ratings

	Parameter	JANTX2N6845, JANTXV2N6845	Units
I _D @ V _{GS} = -10V, T _C = 25°C	Continuous Drain Current	-4.0	A
I _D @ V _{GS} = -10V, T _C = 100°C	Continuous Drain Current	-2.6	
I _{DM}	Pulsed Drain Current ①	-16	
P _D @ T _C = 25°C	Max. Power Dissipation	20	W
	Linear Derating Factor	0.16	W/K ⑤
V _{GS}	Gate-to-Source Voltage	±20	V
dv/dt	Peak Diode Recovery dv/dt ③	-5.0	V/ns
T _J	Operating Junction	-55 to 150	°C
T _{STG}	Storage Temperature Range		
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10.5 seconds)	
	Weight	0.98 (typical)	g

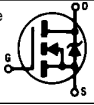


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Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain-to-Source Breakdown Voltage	-100	—	—	V	V _{GS} = 0V, I _D = -1.0 mA
ΔBVDSS/ΔT _J	Temperature Coefficient of Breakdown Voltage	—	-0.10	—	V/°C	Reference to 25°C, I _D = -1.0 mA
RDS(on)	Static Drain-to-Source On-State Resistance	—	—	0.60	Ω	V _{GS} = -10V, I _D = -2.6A ^④
		—	—	0.69		V _{GS} = -10V, I _D = -4.0A
VGS(th)	Gate Threshold Voltage	-2.0	—	-4.0	V	V _{DS} = V _{GS} , I _D = -250μA
gfs	Forward Transconductance	1.25	—	—	S (r)	V _{DS} > -15V, I _{DS} = -2.6A ^④
IDSS	Zero Gate Voltage Drain Current	—	—	-25	μA	V _{DS} = 0.8 x Max Rating, V _{GS} = 0V
		—	—	-250		V _{DS} = 0.8 x Max Rating V _{GS} = 0V, T _J = 125°C
IGSS	Gate-to-Source Leakage Forward	—	—	-100	nA	V _{GS} = -20V
IGSS	Gate-to-Source Leakage Reverse	—	—	100	nA	V _{GS} = 20V
Qg	Total Gate Charge	4.3	—	16.3	nC	V _{GS} = -10V, I _D = -4.0A
Qgs	Gate-to-Source Charge	1.3	—	4.7		V _{DS} = Max. Rating x 0.5 see figures 6 and 13
Qgd	Gate-to-Drain ("Miller") Charge	1.0	—	9.0		
td(on)	Turn-On Delay Time	—	—	60	ns	V _{DD} = -50V, I _D = -4.0A, R _G = 7.5Ω, V _{GS} = -10V see figure 10
t _r	Rise Time	—	—	100		
td(off)	Turn-Off Delay Time	—	—	50		
t _f	Fall Time	—	—	70		
LD	Internal Drain Inductance	—	5.0	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die. 
LS	Internal Source Inductance	—	15	—		Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
C _{iss}	Input Capacitance	—	380	—	pF	V _{GS} = 0V, V _{DS} = -25V f = 1.0 MHz see figure 5
C _{oss}	Output Capacitance	—	170	—		
C _{rss}	Reverse Transfer Capacitance	—	45	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	-4.0	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier. 
I _{SM}	Pulse Source Current (Body Diode) ①	—	—	-16		
V _{SD}	Diode Forward Voltage	—	—	-4.8	V	T _j = 25°C, I _S = -4.0A, V _{GS} = 0V ^④
t _{rr}	Reverse Recovery Time	—	—	200	ns	T _j = 25°C, I _F = -4.0A, di/dt ≤ -100A/μs V _{DD} ≤ -50V ^④
Q _{RR}	Reverse Recovery Charge	—	—	3.1	μC	
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .				

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{thJC}	Junction-to-Case	—	—	6.25	K/W	Typical socket mount
R _{thJA}	Junction-to-Ambient	—	—	175		

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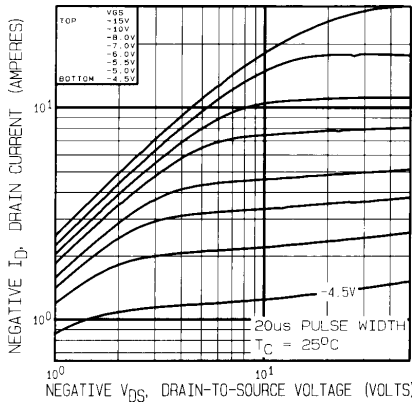


Fig. 1 — Typical Output Characteristics
 $T_C = 25^\circ\text{C}$

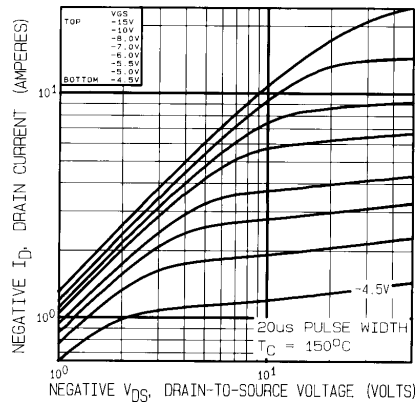


Fig. 2 — Typical Output Characteristics
 $T_C = 150^\circ\text{C}$

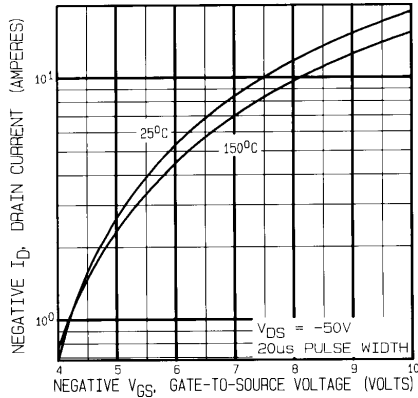


Fig. 3 — Typical Transfer Characteristics

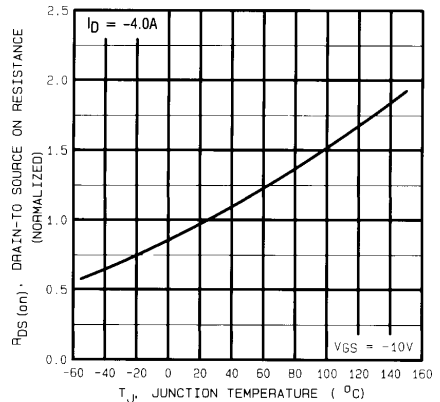


Fig. 4 — Normalized On-Resistance Vs. Temperature

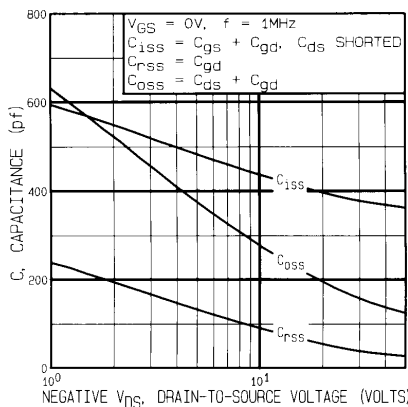


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

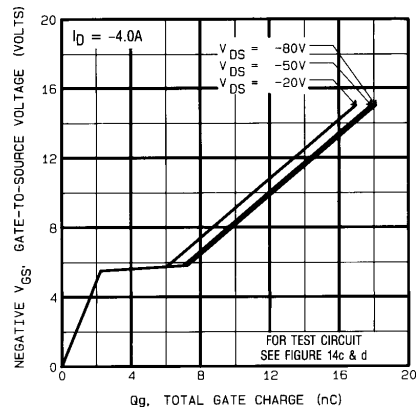


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

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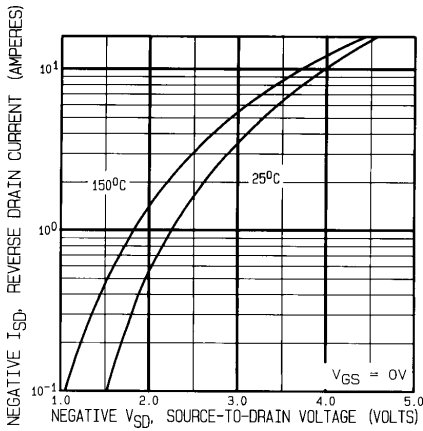


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

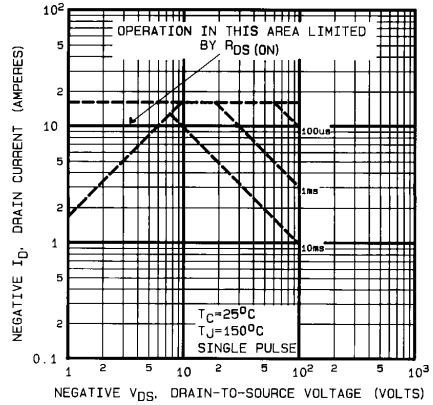


Fig. 8 — Maximum Safe Operating Area

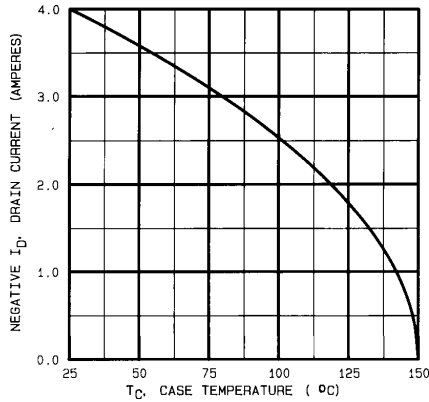


Fig. 9 — Maximum Drain Current Vs. Case Temperature

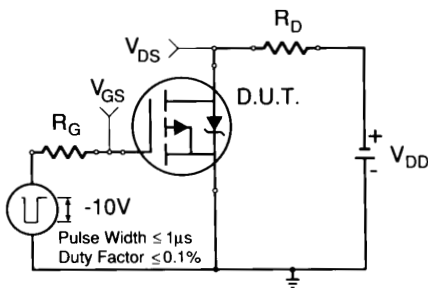


Fig. 10a — Switching Time Test Circuit

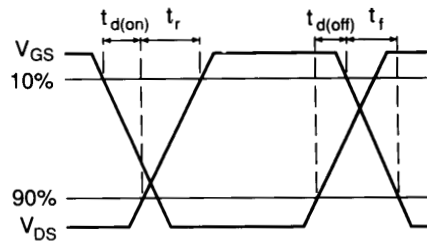


Fig. 10b — Switching Time Waveforms

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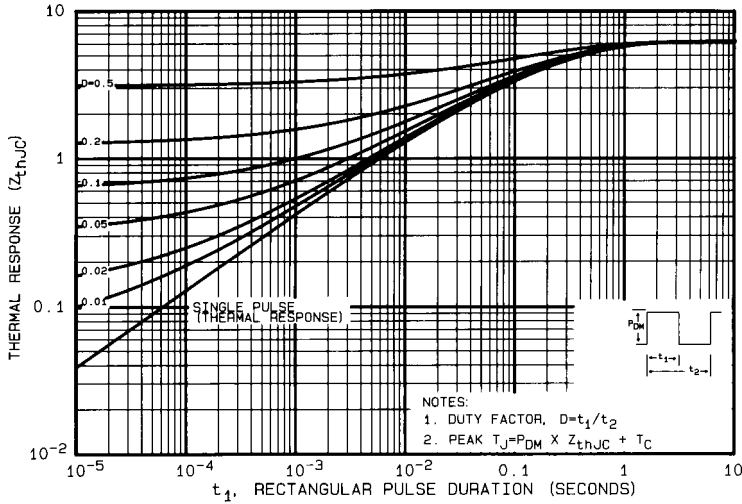


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

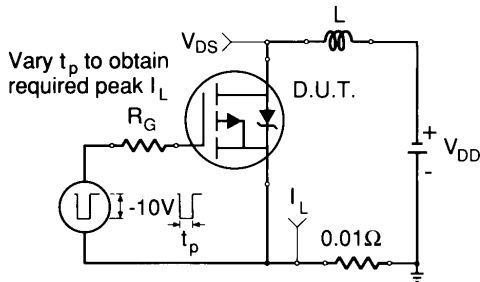


Fig. 12a — Unclamped Inductive Test Circuit

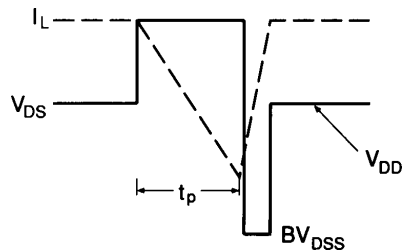


Fig. 12b — Unclamped Inductive Waveforms

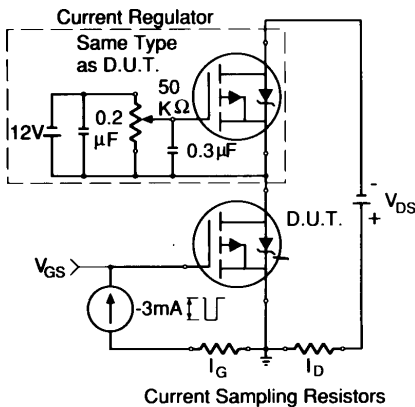


Fig. 13a — Gate Charge Test Circuit

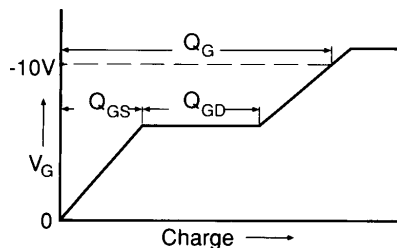


Fig. 13b — Basic Gate Charge Waveform

